Technical Data Sheet

FeedBond® FP-1725-TE4

Low cure temperature Conductive Adhesive

Introduction:

FeedBond®FP-1725-TE4 is an electrically conductive adhesive. It is designed for low temperature curing or fast cured at high temperature in oven. Suitable for automatic jetting machine.

Characteristics:

- Low cure temperature
- Suitable for automatic jetting
- Fast cured at high temperature
- Good adhesion and Low volume resistivity

UNCURED PROPERTIES		**TEST DESCRIPTION**	**TEST METHOD**
Appearance	Silver		
Viscosity @ 25℃	12000±3000 cps	Brookfield DV-III/CP-51 @ 5rpm	FT-P006
Thixotropic Index @ 25℃	3.6~4.6	Brookfield DV-III/CP-51 Visc. @ 0.5rpm/Visc. @ 5rpm	FT-P008
Grind	< 20μm	Grind meter	FT-P026
Work Life @ 25℃	>6 hrs	25% increase in visc. @ 5rpm	FT-P024
Shelf Life@ -40℃	6 months		FT-P018
CURE CONDITION		**TEST DESCRIPTION**	**TEST METHOD**
Standard Cure Condition in oven		90~120min @80℃ 30min @100℃	
Die Shear Strength @ 25℃	>600 g/die	45mil × 45mil Si die on Ag LF	FT-M012

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PHYSIOCHEMICAL PROPERTIES-POST CURE		TEST DESCRIPTION	TEST METHOD
Glass Transition Temperature (Tg)	132℃	DMA 3 Point Bending Mode	FT-M014
Coefficient of Thermal Expansion		TMA Expansion Mode	FT-M016
Below Tg(α1)	68ppm/℃		
Above Tg(α2)	212 ppm/℃		
Storage Modulus			
@25℃	5893MPa	Dynamic Mechanical Thermal Analysis using <1.6mm thick specimen	FT-M019A
@150℃	1268MPa		
@250℃	263MPa		
THERMAL ELECTRICAL PROPERTIES-POST CURE		**TEST DESCRIPTION**	**TEST METHOD**
Volume resistivity	<0.0005Ω · cm	Cure 30min in oven @100℃ 4-point probe	FT-P017
Thermal conductivity	2.62W/mK	Hot Disk	FT-P022

p.s. The tables shown above are typical values only. If you need to write a specification, please request our current Standard Release Specification.

Instruction

Thawing

Place the container to stand vertically for 30min ~90min.**DO NOT** open the container before adhesive reaches ambient temperature to prevent the moisture condensation. Any moisture that collects on the thawed container should be removed prior to use. Adhesives that appear to have separated should not be used.

Storage

Adhesive should be stored @ -40℃. The shelf life of the material is only valid when the material has been stored at the correct storage condition.

Availability

FeedBond adhesives are packaged in syringes or pots per customer specification. For the details, please contact our Customer Service or sales department.